



Hub of Application Laboratories for Equipment
Assessment in Laser Based Manufacturing



Supported by the
European
Commission



APPOLO project within FP7 framework

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APPOLO Workshop
Lappeenranta, Finland

www.appolo-fp7.eu
FP7 project No 609355



CENTER
FOR PHYSICAL SCIENCES
AND TECHNOLOGY

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- FTMC ■ APPOLO Workshop Lappeenranta ■ 16-Jun-15 ■ p. 2 ■

- **focuses on** emerging innovative laser technologies and processes, which need to be customised, tested and validated :
 - **Customized** – service of application labs for trials;
 - **Tested** – experiments at variable conditions;
 - **Validated** – reliability and process quality assessment in the close-to-manufacturing environment.

 - **exploits** the unique combination of distributed knowledge in
 - academic application labs,
 - equipment producers,
 - system integrators and
 - end-users
- to enable the development of innovative processes, products and machineries for industrial laser material processing applications.
-
- **seeks** to establish and coordinate the **Hub of laser application laboratories** to provide the high-quality integrated services.

■ establish and coordinate connections between

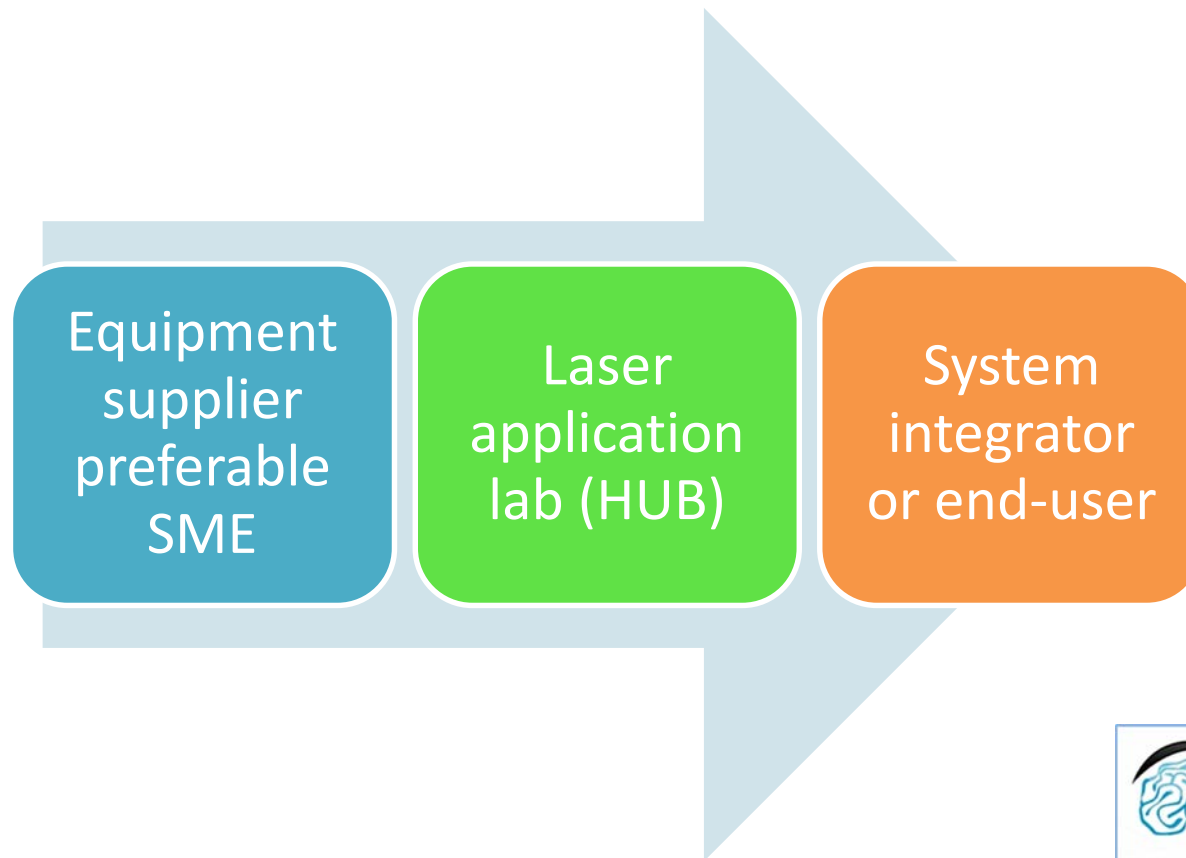
- **the end-users**, which have demand on laser technologies for (micro)fabrication;
- knowledge accumulated in **the application laboratories** of research institutes and universities;
- **the laser equipment manufacturers** (preferable SMEs: for integration, lasers, beam control and guiding, software, etc.),

&

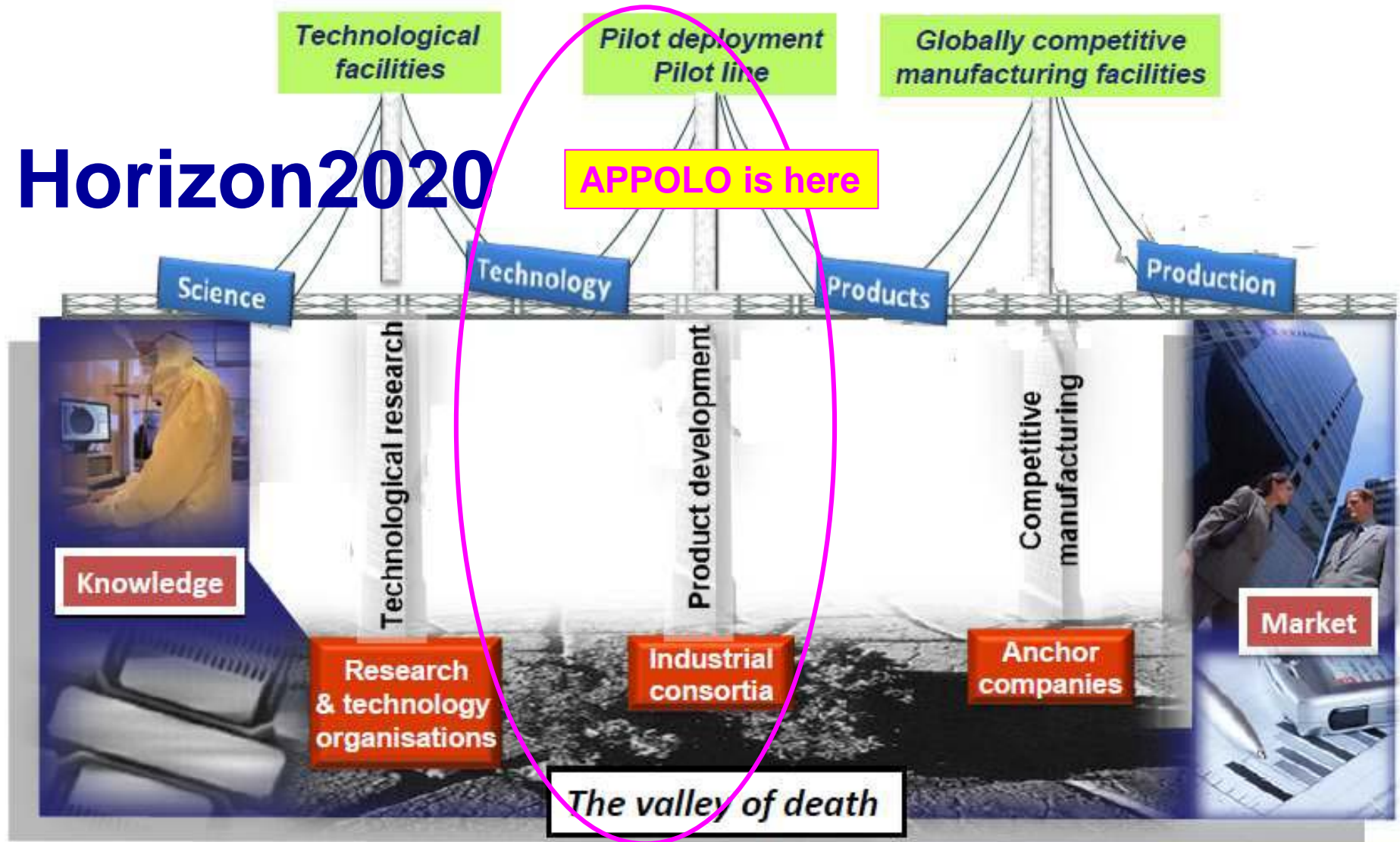
■ facilitate

- faster validation of the process feasibility
- adaptation or customization of the technology & equipment for manufacturing conditions, including:
 - reliability of components;
 - their interaction;
 - assessment of the dedicated production processes;
 - process speed, quality and repeatability;
 - economics issues.

Reducing barrier to enter into market with new product
(equipment for laser-based manufacturing)



Horizon2020



EC High Level Group on Key Enabling Technologies Status Report

28/06/2011:

the Three Pillars Bridge to Pass across "Valley of Death"

Technology readiness levels (TRL)

“blue sky”
research

- **TRL1** - basic principles observed
- **TRL2** - technology concept formulated
- **TRL3** - experimental proof of concept

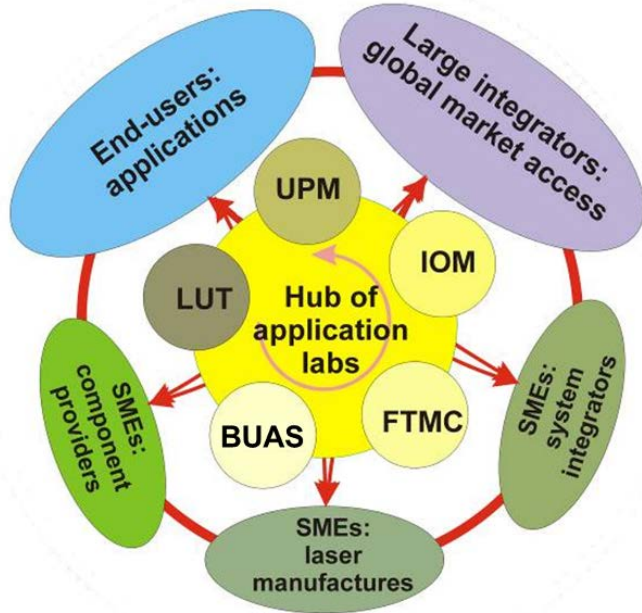
Applied
research

- **TRL4** - technology validated in lab
- **TRL5** - technology validated in relevant environment (industrially relevant environment in case of key enabling technologies)
- **TRL6** - technology demonstrated in relevant environment (industrially relevant environment in case of key enabling technologies)

Technology
development

- **TRL7** - system prototype demonstration in operational environment
- **TRL8** - system complete and qualified
- **TRL9** - actual system proven in operational environment (competitive manufacturing in case of key enabling technologies or in space)

Position of APPOLO and a part of PPP FoF

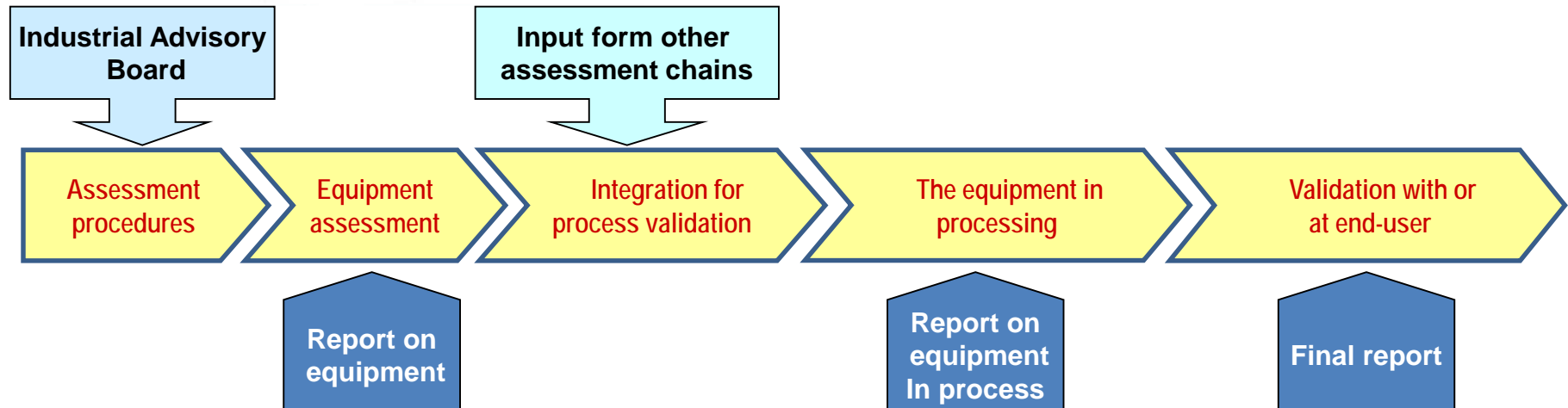


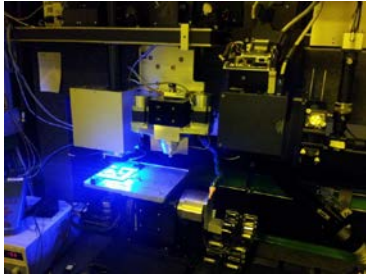
Hub of laser application laboratories

Core of the consortium - **laser application laboratories**:

- around Europe;
- connected to a virtual hub, in order to
- accumulate knowledge and infrastructure
- promote the easy-to-access environment
- develop and validate of laser-based technologies in

the **8+7** equipment assessment value chains:





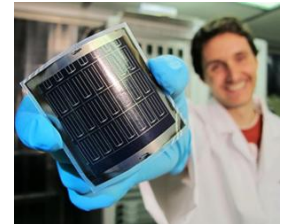
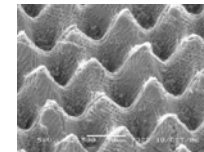
END-USERS:

- *Centro Ricerche Fiat SCPA*
- *Daetwyler Graphics AG*
- *Abengoa Solar New Technologies SA*
- *Mondragon Assembly Sociedad Cooperativa (SME)*
- *Sachsische Walzengravur GmbH*
- *Bioage SRL (SME)*
- *Flisom AG (SME)*
- ...



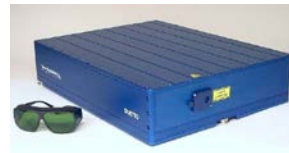
APPLICATION LABORATORIES:

- *Center for Physical Sciences and Technology*
- *Leibniz-Institut für Oberflächenmodifizierung e.V.*
- *Bern University of Applied Sciences*
- *Lappeenranta University of Technology*
- *Universidad Politécnica de Madrid*

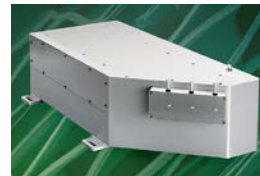


SUPPLIERS:

- *Ekspla UAB (SME)*
- *Time Bandwidth Products AG (SME)*
- *OneFive GmbH (SME)*
- *Next Scan Technology BV (SME)*
- *Amsys Ltd. (SME)*
- *ELAS UAB (SME)*
- *Lightmotif BV (SME)*
- ...



Picosecond



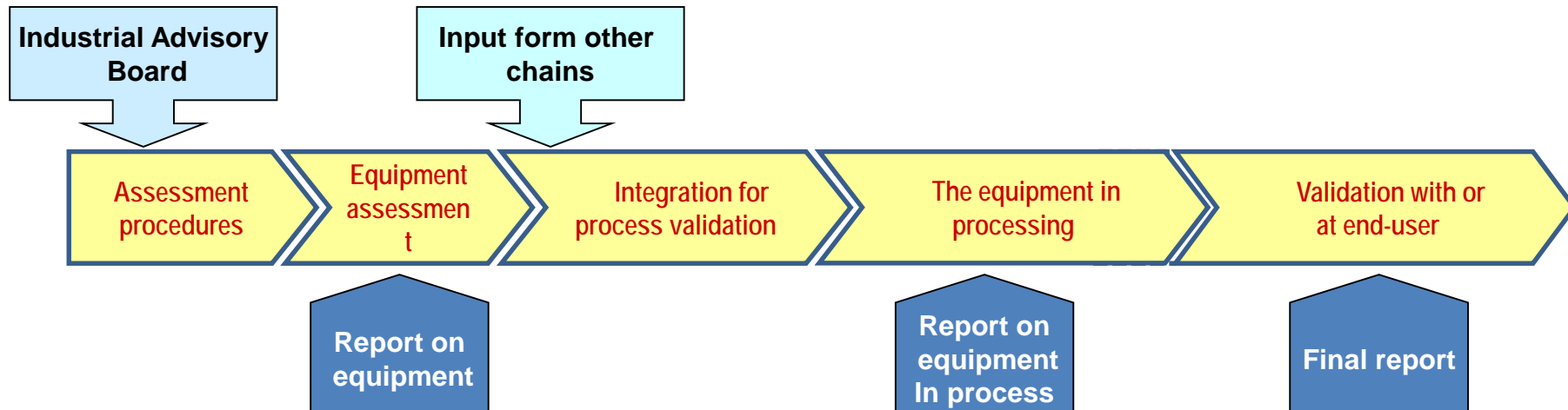
MATERIALS:

- *Eidgenössische Materialprüfungs- und Forschungsanstalt*

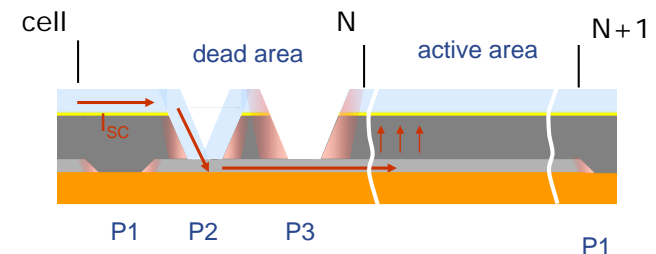
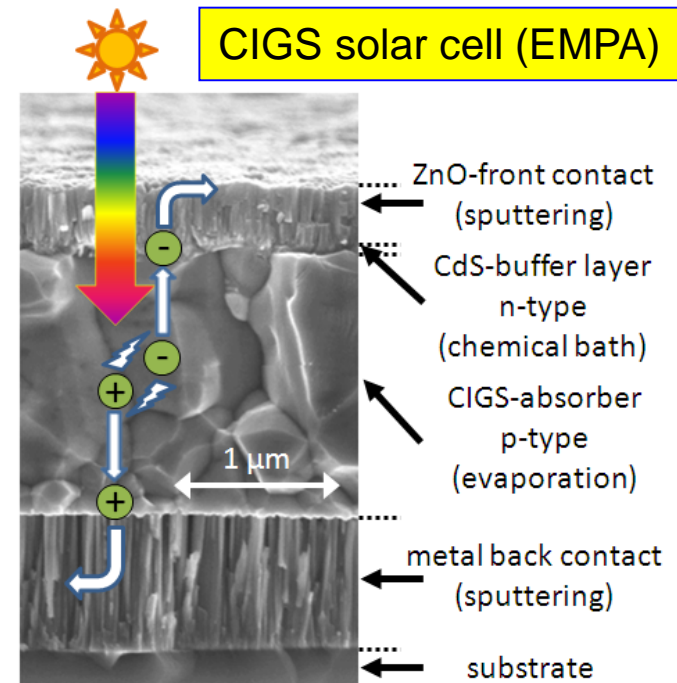
IPR MANAGEMENT & EXPLOITATION

- *engage AG (SME)*

- **Thin film CIGS solar cell scribing with picosecond lasers:**
 - Novel lasers, scribing concepts, intelligent laser beam control & integration into machines
- **Laser surface texturing:**
 - New laser, high speed & precision laser texturing & dedicated nanostructures for surface functionalisation;
 - Integration in to machines for automotive and printing/decorative applications
- **Laser patterning for flexible 3D electronics:**
 - New patterning concepts, 3D patterning; Integration with other techniques (ink-jet, LIFT)
- Parallel activities on **sensing and monitoring techniques** for processing and validation.



- Assessment of **equipment** and its interaction
 - 1.34 μm ps-laser
 - ps-fiber laser with pulse on demand feature
 - fast polygon scanner
 - on-line scribing process monitoring tool
- Integration & assessment in the process
- Final validation at end-user facility
- Approaches for thin-film CIGS solar cells on different substrates (glass, polymer, metal)
- **Key issues:**
 - selectivity in layer processing;
 - narrow “dead” interconnection zone;
 - minimised residual side effects;
 - high process speed.

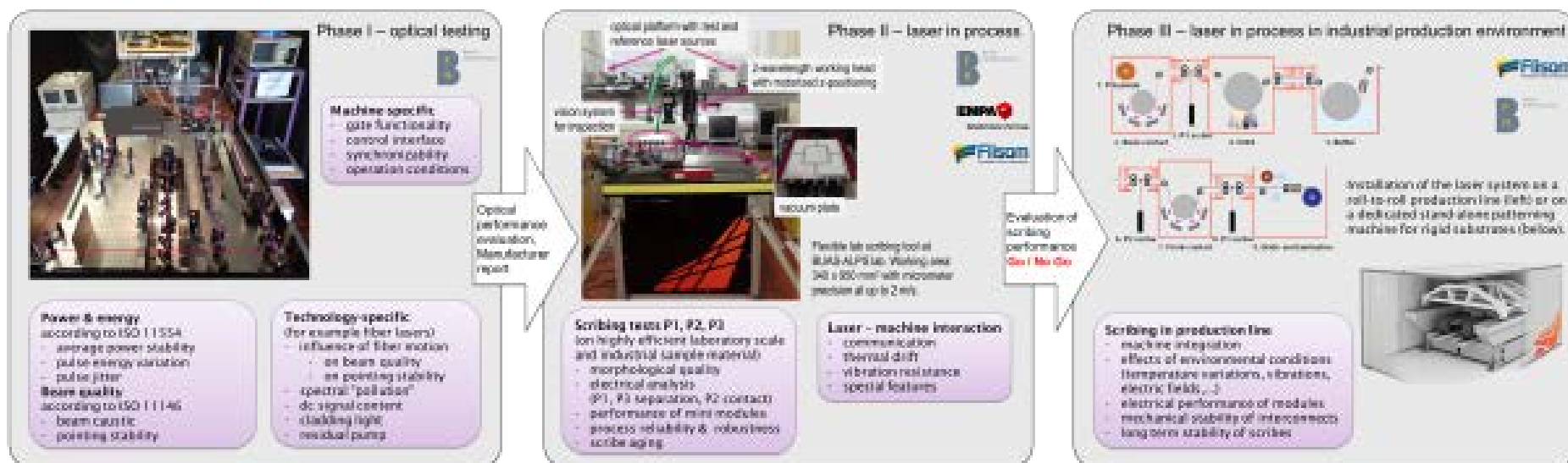


Standard monolithic integrated interconnect scheme: P1, P2 and P3 scribing processes performed between deposition steps

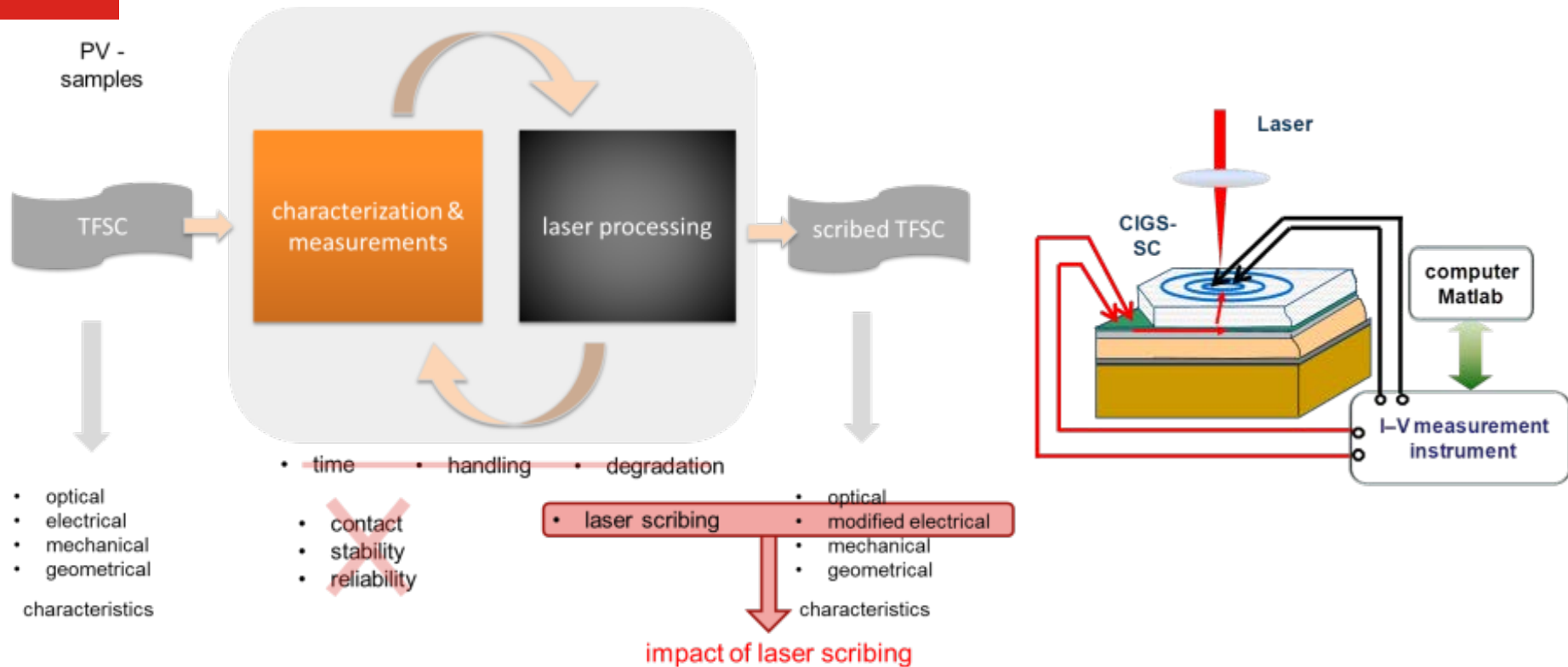
Phase I Optical testing

Phase II Laser in process

Phase III Laser in process in industrial production environment



Schematic representation of the 3-stage assessment process in CIGS solar cell scribing



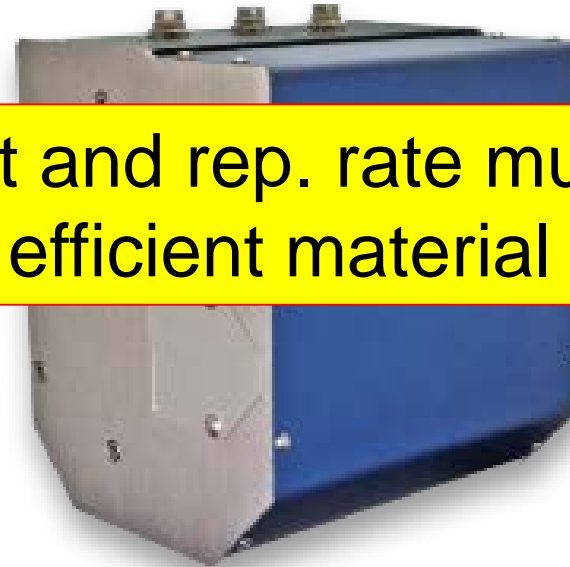
Approach of **in-process measurement** of the laser impact on the electrical properties of functional devices,

Verification of new equipment

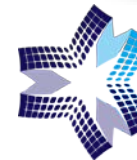
Pulse energy, focus spot and rep. rate must be adjusted together for most efficient material removal



Atlantic ps laser
13 ps, > 60 W, 1 MHz



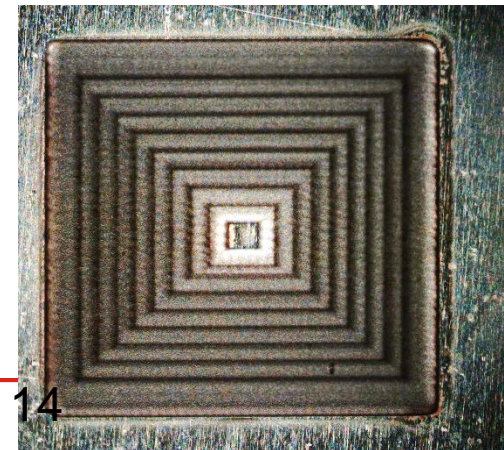
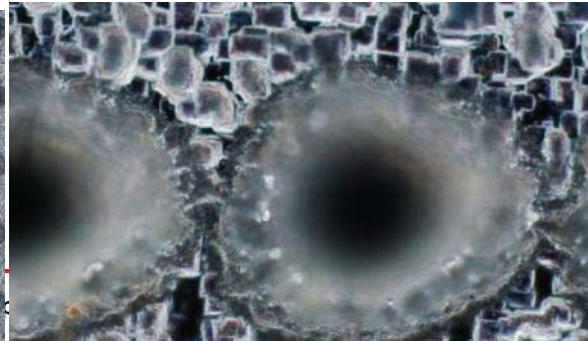
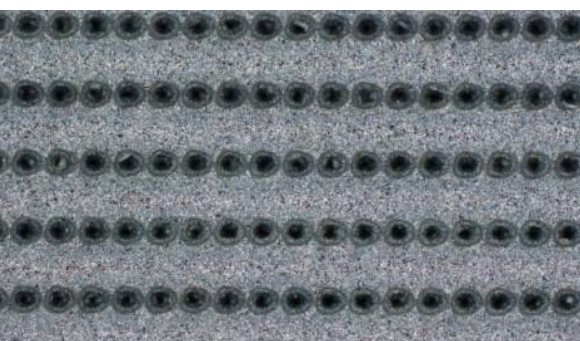
Polygon
scanner
100 m/s



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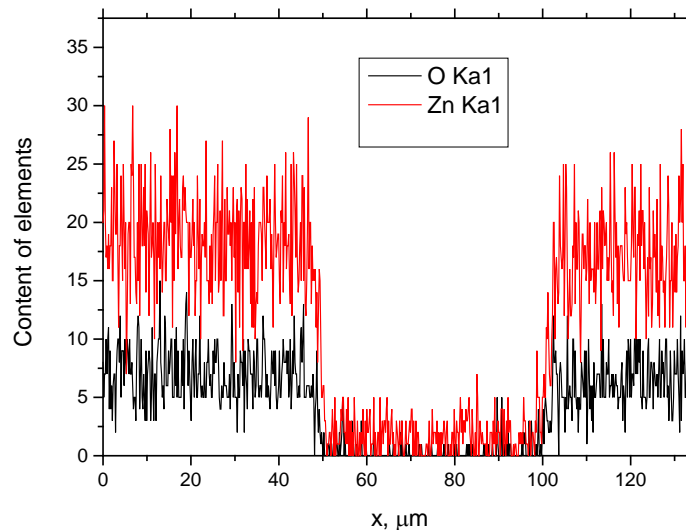
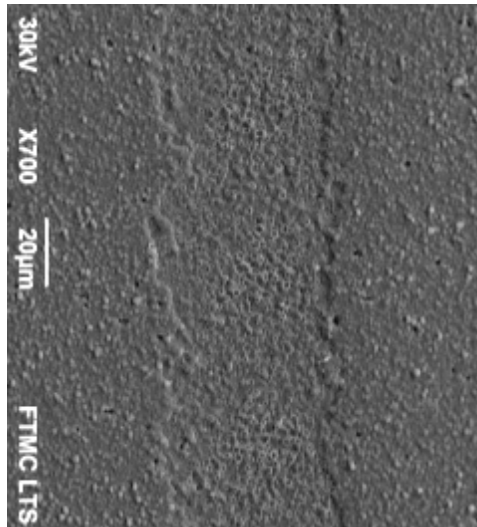
3D

Repeatability: 2000 times @ 50 m/s



P3 type scribe is used for isolation of the adjacent cells:

- ❑ Removal only the top-contact or the full structure up to the molybdenum back-contact.
- ❑ TCO removal requires less laser power and small laser pulse overlap.



EDS analysis



30 W, 987 kHz, 49.35 m/s, single pass

ps-laser and polygon scanner

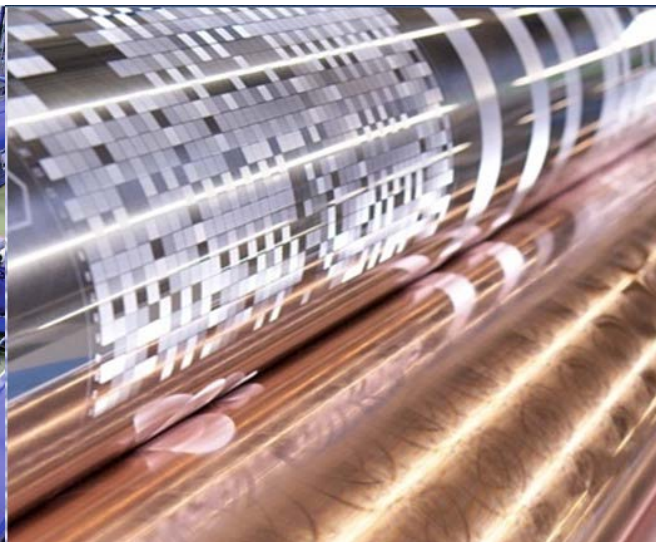


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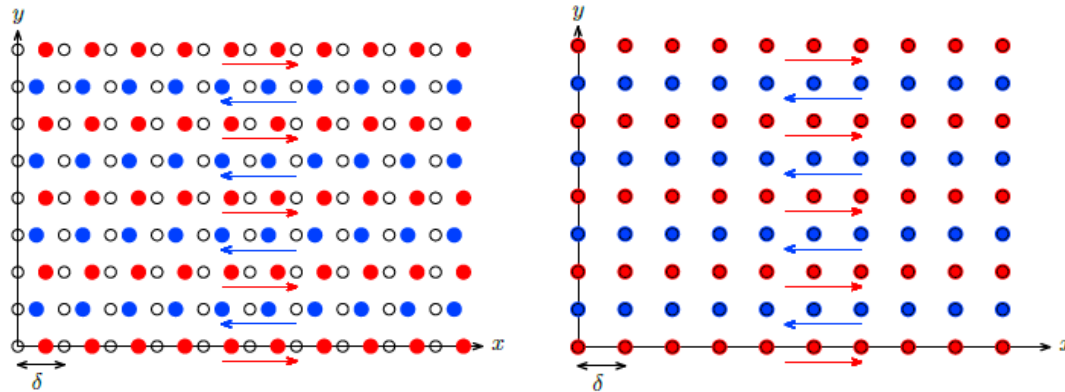
High resolution 3D micro-structuring with ultra-short pulse lasers for embossing

- evaluation and validation of the **lasers and fast scanning** polygon devices;
- integration of the fast scanning devices on an **existing gravure setup**;
- evaluation of process strategies and process parameters **for industrial production**;
- validation of equipment in development of **special structures**.

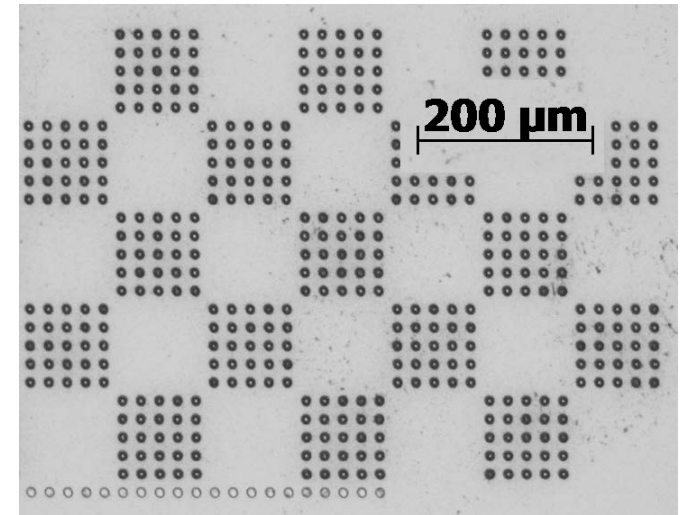


Precise control of galvoscaner at high speed

Synchronized bidirectional scanning



Unaligned and aligned spot positions



The used galvoscaner offers two different tuning modes:

1. Higher precision and work up to a scan velocity of **3 m/s**.
2. Scan speeds up to **15 m/s** but reduced precision at high speeds.

In both scanning modes, there is a trade-off between precision and speed.

The processing time is divided by two from unidirectional to bidirectional mode.

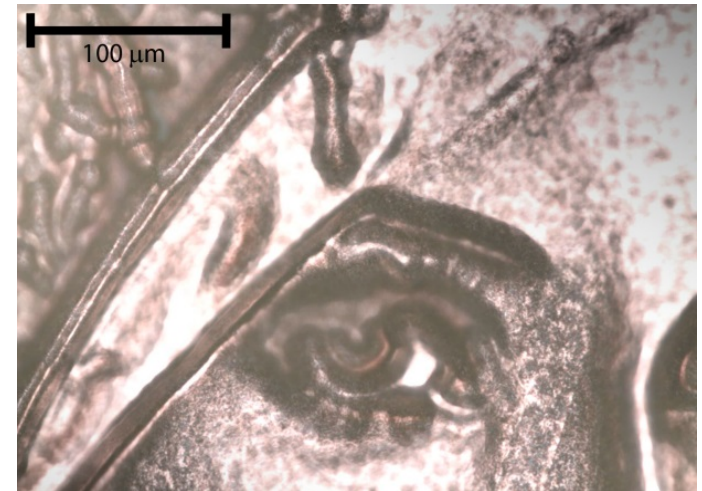
- Slicing the **grayscale image** into a given number of levelled black and white images.
- The **black and white images** are then processed one by one.



Bern University
of Applied Sciences



Grayscale and black and white image



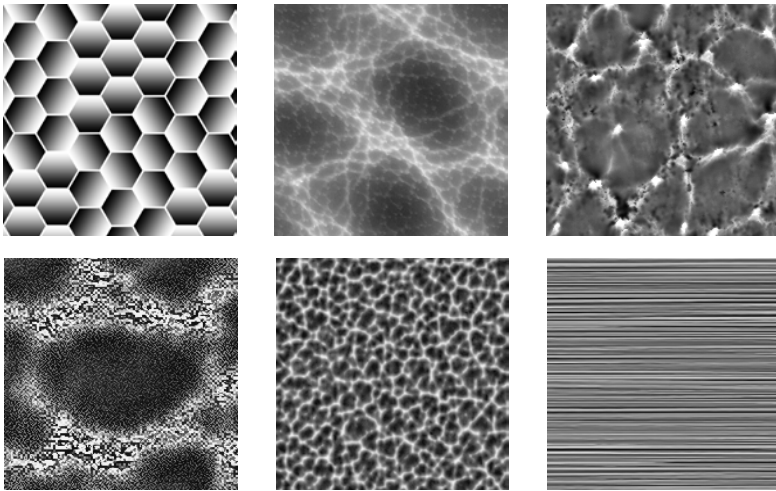
Detail of machined structure

Result with **100 slices** at 532 nm, 1 MHz, 1.2 W and 3 µm pitch.

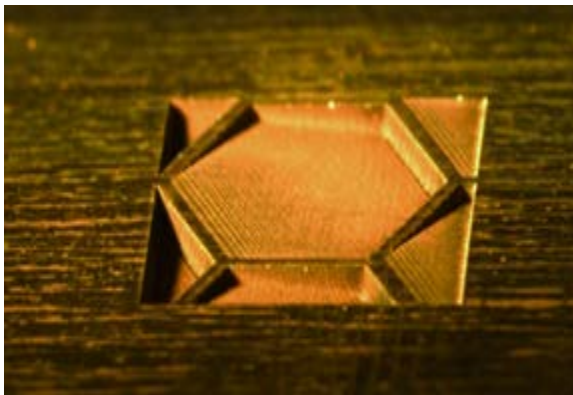
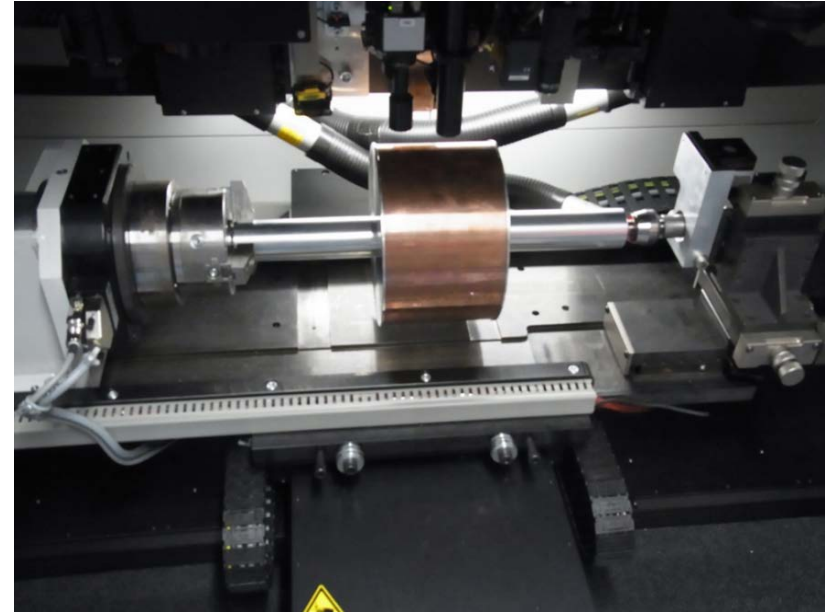
Image size on target is approximately **1.5x1.5 mm²**.

Processing time of one layer is 1.2 s and the overall process time is **2 minutes**.

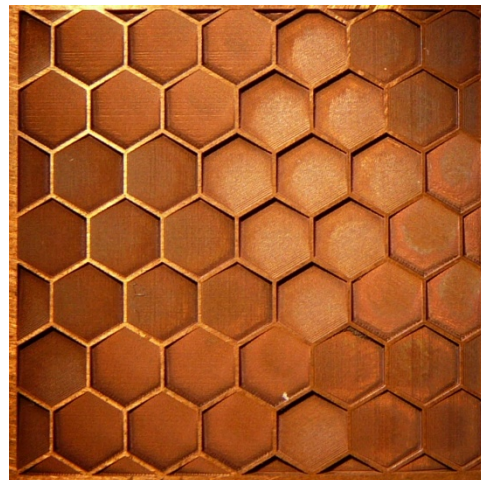




Examples of grey scale images of application related topographies



Honeycomb structure in copper laser written by ps-laser



IOM

SWG

Daetwyler
Graphics

supported by



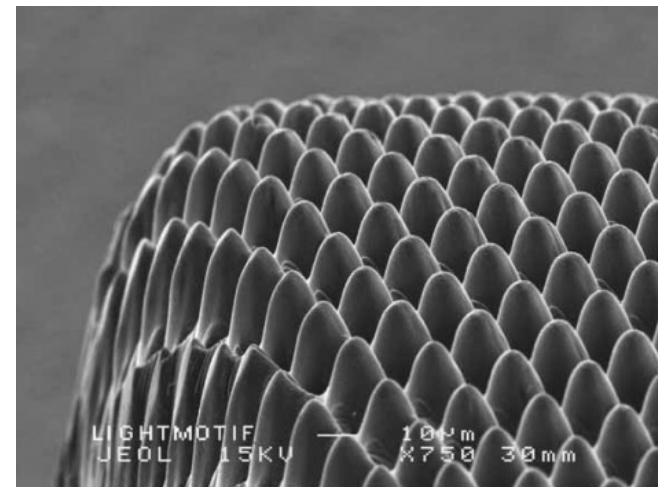
- Surface engineering – to create **soft-touch** and **anti-glare effects** by functional textures on molds for automotive industry
- Assessment and optimization for **3D mold texturing** method
- Validation of combined technology by production of real **automotive** part with added soft-touch texture



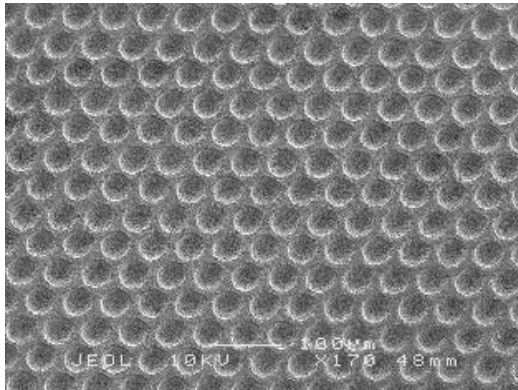
Leather imitation on moulded surfaces car's interior parts.

Applications of surface texturing include:

- **Friction reduction** in lubricated contacts: on pistons or bearing surfaces
- Change of the **haptic properties** of surfaces: to reduce skin friction and to create silky soft surfaces
- Changing **wetting properties** of surfaces: super water repelling surfaces
- Change of **cell growth** on surfaces: the attachment of bone to implants



Laser texturing of moulds



SEM measurements of one test texture



Lightmatif
ultrafast pulsed laser machining



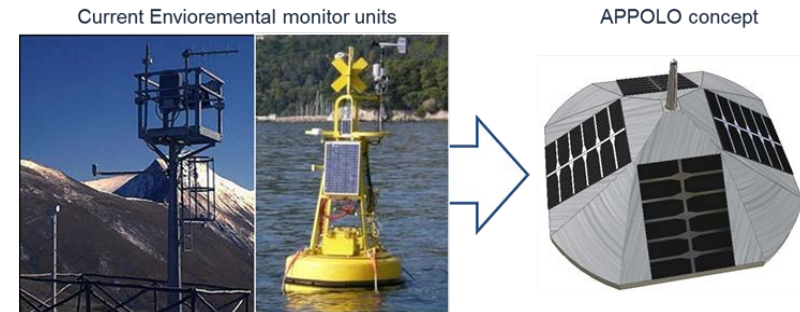
Two laser textured mould inserts



- Validate reliable schemes for **direct writing of 3D wiring** by laser radiation.
 - overcome basic problems of current state of the art;
 - process standard plastics instead of using highly specialized costly material;
 - saving resources by adding material for laser functionalisation.
- Demonstration of new capabilities in surface functionalisation by lasers for 3D wiring and **flexible electronics**;
- Assessment of new laser beams for writing 3D / flexible electronics;
- Validation of the electric interconnections made by lasers in **real conditions**.



Integrated switches in central console for interior commands.



Example of APPOLO concept as applied in current environmental monitor unit.

Molded interconnect devices (MID)



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There are no limits to **MID**!



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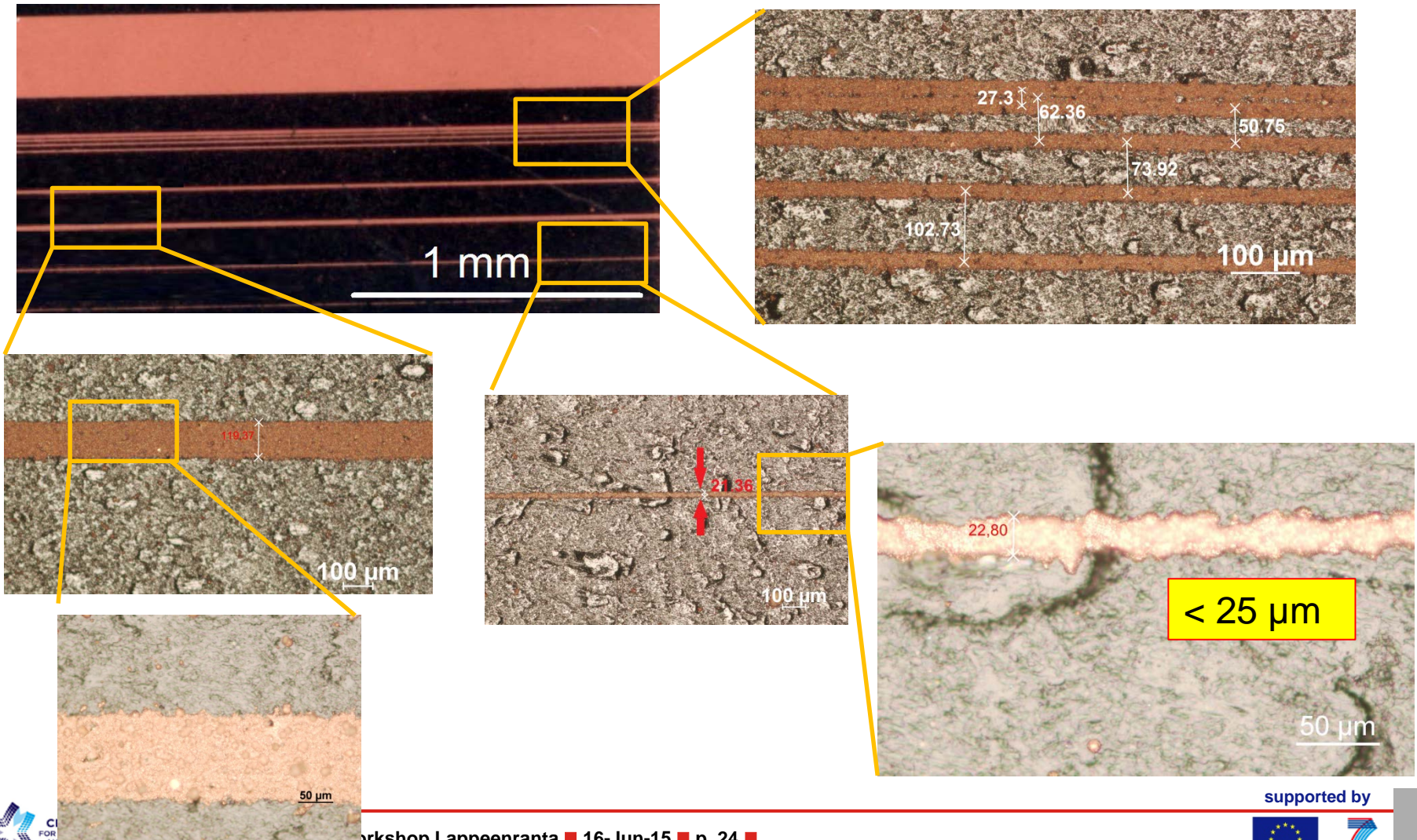


Selectivity of plating



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Laser-modified surface of polymer + electroless plating



Application for electronics

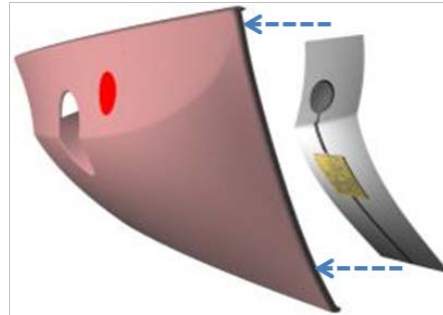
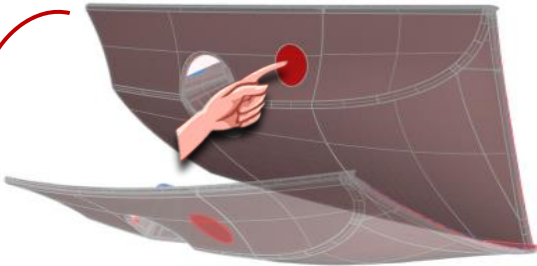


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Dashboard Electronic Design

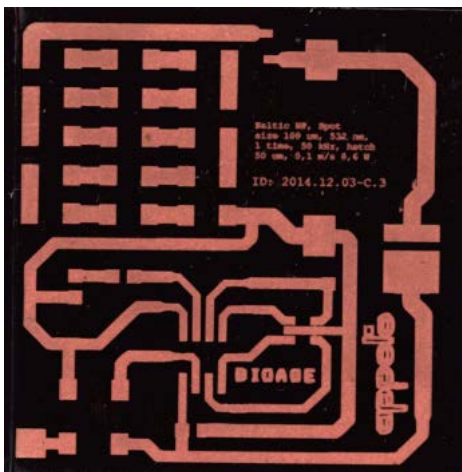


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appolo

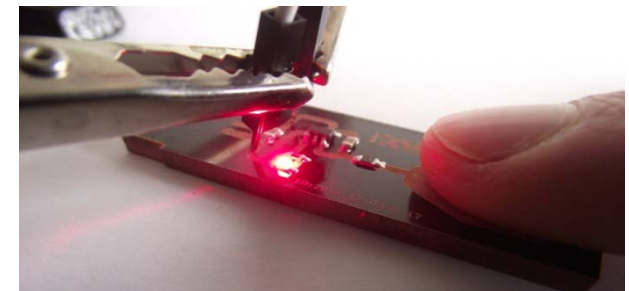
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Conductive tracks for
Temperature sensor



BIOAGE



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New materials and approaches



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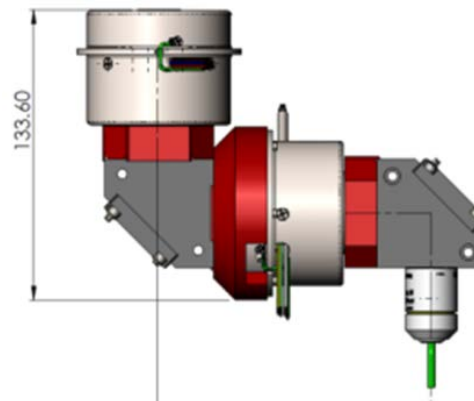
SABIC Innovative Plastics:
NX07354 (PC/ABS)
DX11354 (PC)



CRF Carbon-based
materials

| Material: | NX07354 | DX11354 | PP X1 | PPX2 | PPX3 |
|---|---------|---------|--------|--------|-------|
| Sheet resistance of plated surface [Ω/\square] | 0.036 | 0.029 | 0.0177 | 0.0871 | 0.025 |
| Laser scanning [m/s] speed | 0.1 | 0.1 | 1 | 1 | 1 |
| Number of scans | 20 | 1 | 1 | 1 | 1 |

On a way to real 3D



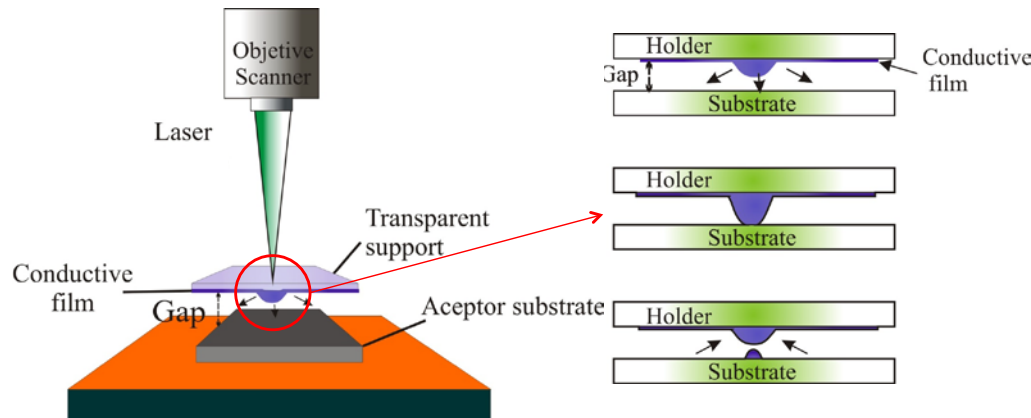
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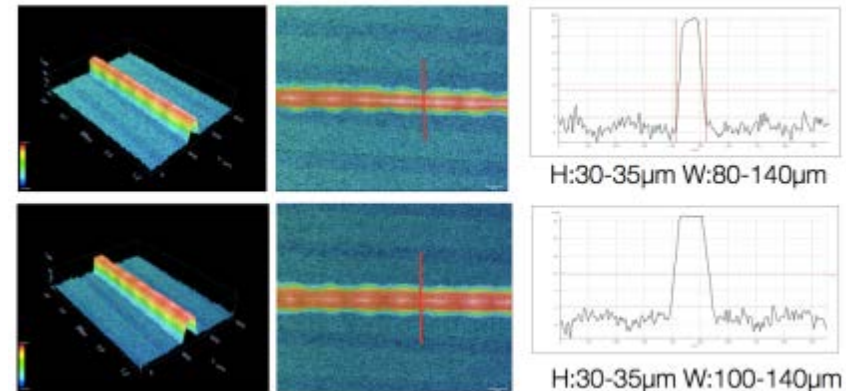
- Laser direct writing of flex electronics and **photovoltaics** in planar geometry will be assessed and validated:
 - adding material techniques (especially **LIFT**)
 - post-deposit **firing/curing techniques** using laser technology.



POLITÉCNICA



Principle of LIFT process for metallisation of thin-film solar cells



LIFT silver paste line obtained at UPM at industrial velocities (2 m/s)

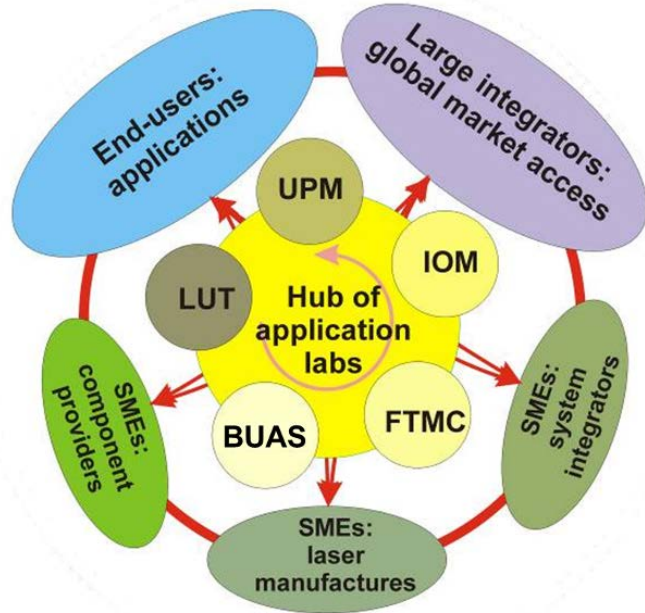
Standard way is to use ns-lasers, however, ps-lasers provide benefits in the line width

- Development and validation of **on-line monitoring tools** and beam control systems which are necessary:
 - **process control** during the assessment experiments;
 - on-line tools to be assessed and integrated into laser processing systems.

- **On-line tools for integration** into laser processing systems:
 - **surface profile monitoring tool** with polygon scanner;
 - **auto-focusing unit** for laser processing in 3D electronics.

APPOLO Workshop

- Online Monitoring in Laser Processing
- 5Th of June, 2015
- LUT Laser, Future Factory, Tuotantokatu 2, Lappeenranta, Finland



■ Industrial Advisory Board (IAB)

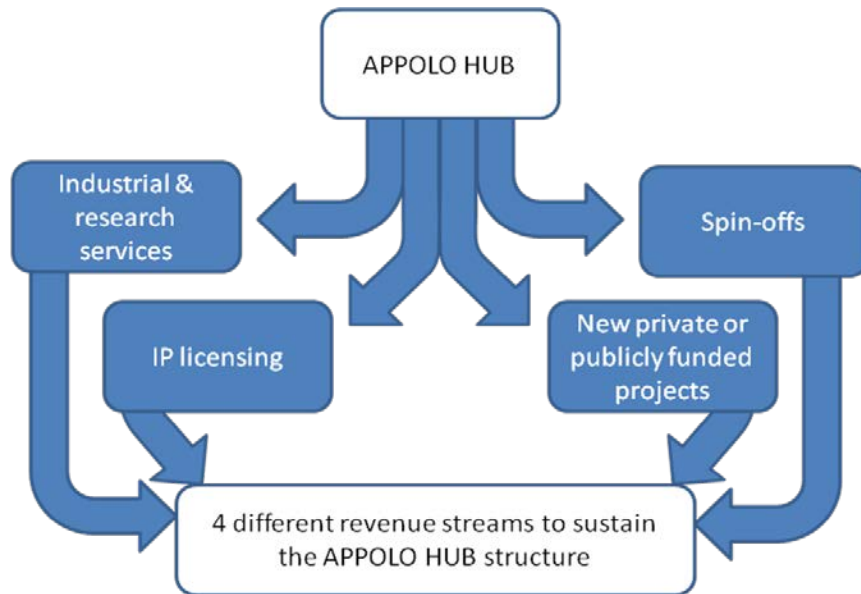
- industrial partners in the consortium
 - end-user companies interested in the project results but standing outside the consortium
 - industrial associations like EPIC
- ## ■ IAB: technical requirements and procedures for assessment in specific application fields

■ Objectives of the HUB:

- prepare procedures for assessment service;
- manage and analyze of assessment projects;
- compare with alternative technologies.

■ HUB activities are intended to prepare

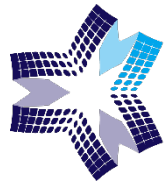
- operational procedures for efficient assessment execution;
- high-quality assessment service;
 - assessment procedures (IAB)
 - standards for assessment
 - certification of equipment
- attract potential HUB customers:
 - **equipment suppliers** looking for applications/validation;
 - **end-users** looking for solutions (equipment which can provide technology);
 - **system integrators** –specific requests they do not have possibility to test at home.
- pave a way for sustainable operation of HUB as laser technology service provider.



1. **Services:** HUB participants perform services either for industrial or public/research customers (e.g. patterning, validation, ...)
2. **IP licensing:** Jointly developed IP can be licensed centrally, avoiding costly and timely individual negotiations
3. **New projects:** The HUB can act as a single entity to acquire new projects and can thus bring unparalleled depth, knowledge and excellence to bear.
4. **Spin-Offs:** New companies, developed either in tandem with corporate partners or as spin-offs based on HUB IP can generate significant returns when the HUB exits its position (i.e. sale of shares, IPO).



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BIOAGE



MONDRAGON
ASSEMBLY



Materials Science & Technology



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AMSYS, LTD.



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Daetwyler
Graphics

6 research entities & 16 companies, more 16 companies will join